L Number	Hits	Search Text	DB	Time stamp
1	261698	(alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or	USPAT;	2003/01/30 12:23
	1	photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or	US-PGPUB;	
		develop\$4)	ЕРО; ЈРО;	
		• *	DERWENT;	
			IBM_TDB	
2	47893	((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or	USPAT;	2003/01/30 12:24
2		photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or	US-PGPUB,	
		develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)	EPO; JPO;	
		develope 1)) state (etalias of fallio 10 1 al	DERWENT;	
	İ		IBM_TDB	
3	1012	(((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist or	USPAT;	2003/01/30 12:24
	1012	photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or	US-PGPUB;	
		develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)) and	EPO; JPO;	
		216/\$.ccls.	DERWENT;	
		210/@.ccis.	IBM_TDB	i
5	21	((((alignment or tab or alet or nin) some (mosk\$4 or nottern\$4 or regist	USPAT;	2003/01/30 12:40
	31	((((alignment or tab or slot or pin) same (mask\$4 or pattern\$4 or resist	US-PGPUB;	2003/01/30 12.40
		or photoresist or photosensitiv\$3 or photolithograph\$5 or imag\$4 or		
		develop\$4)) same (etch\$5 or remov\$4 or laser or ablat\$4)) and	EPO; JPO;	
		216/\$.ccls.) and 216/17.ccls.	DERWENT;	1
			IBM_TDB	2002/01/20 12 46
	37567	(metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12:46
		metallization) near4 (mask\$4)	US-PGPUB;	
			ЕРО; ЛРО;	
İ			DERWENT;	
ļ			IBM_TDB	
6	3946	((metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12.43
		metallization) near4 (mask\$4)) and (((alignment or tab or slot or pin)	US-PGPUB;	
		same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or	ЕРО; ЈРО;	
		photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4	DERWENT;	
		or laser or ablat\$4))	IBM_TDB	
7	301	((metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12:43
		metallization) near4 (mask\$4)) and ((((alignment or tab or slot or pin)	US-PGPUB;	
		same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or	ЕРО; ЛРО;	
		photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4	DERWENT;	
		or laser or ablat\$4)) and 216/\$.ccls.)	IBM_TDB	
8	7	((metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12:43
	,	metallization) near4 (mask\$4)) and (((((alignment or tab or slot or pin)	US-PGPUB;	
		same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or	EPO; JPO;	
9		photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4	DERWENT;	
		or laser or ablat\$4)) and 216/\$.ccls.) and 216/17.ccls.)	IBM_TDB	
	11851	(metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12:56
	11001	metallization) near1 (mask\$4)	US-PGPUB;	2505,01750 12.50
		meanization) near (maskur)	EPO; JPO;	j
			DERWENT;	
			IBM_TDB	
	1107	((matal\$4 or conner or on or conducting or conductive or trace or	USPAT;	2003/01/30 12:47
10	1196	((metal\$4 or copper or cu or conducting or conductive or trace or		2003/01/30 12.47
		metallization) nearl (mask\$4)) and (((alignment or tab or slot or pin)	US-PGPUB;	
		same (mask\$4 or pattern\$4 or resist or photoresist or photosensitiv\$3 or	EPO; JPO;	
		photolithograph\$5 or imag\$4 or develop\$4)) same (etch\$5 or remov\$4	DERWENT;	
		or laser or ablat\$4))	IBM_TDB	2002/01/20 12 17
11	588	((metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12:47
		metallization) near1 (mask\$4)) and 216/\$.ccls.	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
12	154	((metal\$4 or copper or cu or conducting or conductive or trace or	USPAT;	2003/01/30 12:47
		metallization) near1 (mask\$4)) and 219/\$.ccls.	US-PGPUB;	
			ЕРО; ЛРО;	1
			DERWENT;	
	1		IBM_TDB	

2003/01/30 12:54
2003/01/30 12:54
2003/01/30 12:54
2003/01/30 12:54
2003/01/30 12:54
2003/01/30 12:54
2003/01/30 12:56
2003/01/30 12:57